rev 2.0, 03.01.2019

# **SMC970**

• Infrared LED

• 970 nm, 3.6 mW

• SMD package, Ceramic

• Dimension: 3.0 x 2.0 x 1.1 mm

• Viewing Angle: 136°





## Description

**SMC970** is a surface mount GaAs infrared LED with a typical peak wavelength of **970 nm** and radiation of **18 mW**. It comes in SMD package (ceramic) and is sealed with silicone or epoxy resin.

### Maximum Ratings (TCASE=25°C)

Barranatan	O. mark and	Val	11-26		
Parameter	Symbol	Min.	Max.	Unit	
Power Dissipation	$P_D$		140	mW	
Forward Current	I <sub>F</sub>		100	mA	
Pulse Forward Current *1	<b>I</b> FP		1000	mA	
Reverse Voltage	VF		5	V	
Thermal Resistance	R <sub>THJA</sub>		80	K/W	
Junction Temperature	$T_J$		120	°C	
Operating Temperature	$T_{CASE}$	- 40	+ 100	°C	
Storage Temperature	T <sub>STG</sub>	- 40	+ 100	°C	
Lead Solder Temperature *2	$T_{SLD}$		+ 250	°C	

<sup>\*1</sup> duty=1%, pulse width = 10  $\mu$ s

# Electro-Optical Characteristics (TCASE=25°C)

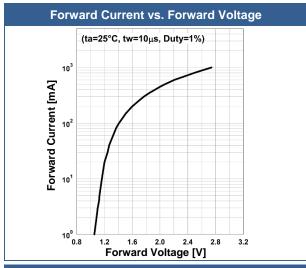
Parameter	Symbol	Conditions	Min.	Values Typ.	Max.	Unit
Peak Wavelength	$\lambda_P$	I <sub>F</sub> =50mA	960		980	nm
Half Width	$\Delta \lambda$	I <sub>F</sub> =50mA		50		nm
Forward Voltage	VF	I <sub>F</sub> =50mA		1.3		V
		I <sub>FP</sub> =1000mA		2.7		
Radiated Power *1	Po	I <sub>F</sub> =50mA		3.6		mW
		I <sub>FP</sub> =1000mA		55		
Radiant Intensity *2	lE	I <sub>F</sub> =50mA		1.2		mW/sr
		I <sub>FP</sub> =1000mA		18		
Viewing Angle	φ	I <sub>F</sub> =50mA		136		deg.
Rise Time	<b>t</b> r	I <sub>F</sub> =50mA		800		ns
Fall Time	<b>t</b> <sub>f</sub>	I <sub>F</sub> =50mA		800		ns

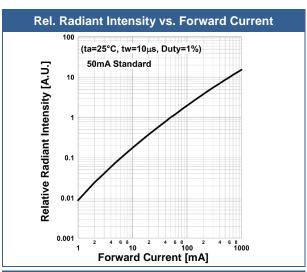
<sup>\*1</sup> measured by S3584-08

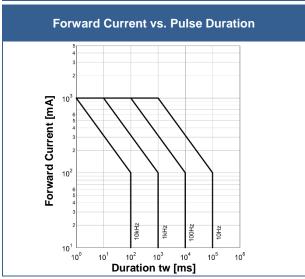
<sup>\*2</sup> must be completed within 3 seconds

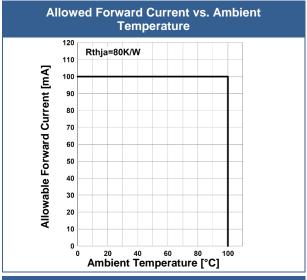
<sup>\*2</sup> measured by CIE127-2007 Condition B

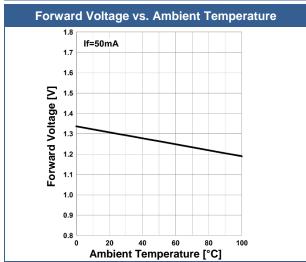


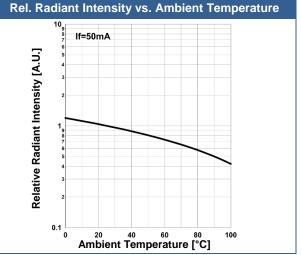










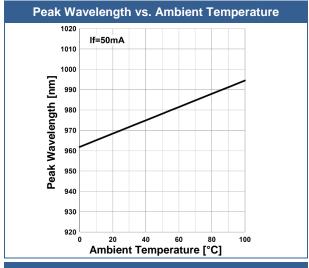


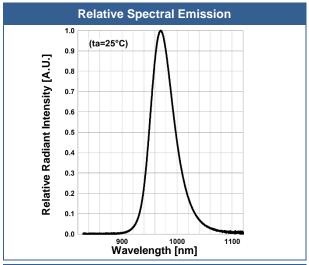


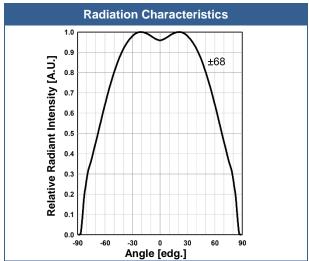
# ROITHNER LASERTECHNIK GmbH

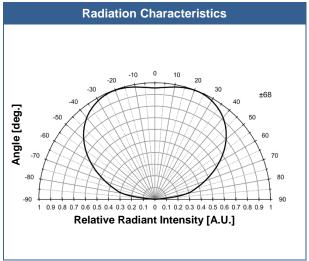
WIEDNER HAUPTSTRASSE 76 IO40 VIENNA AUSTRIA
TEL. +43 I 586 52 43 -0, FAX. -44 OFFICE@ROITHNER-LASER.COM



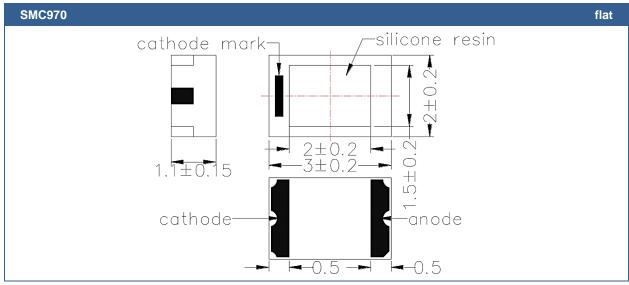








## **Outline Dimensions**



All Dimensions in mm

#### **Precautions**

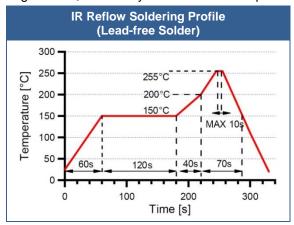
#### Soldering:

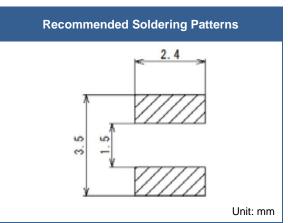
- Do avoid overheating of the LED
- Do avoid electrostatic discharge (ESD)
- Do avoid mechanical stress, shock, and vibration
- Do only use non-corrosive flux
- Do not apply current to the LED until it has cooled down to room temperature after soldering

#### **Recommended soldering conditions:**

This LED is designed to be reflow soldered on to a PCB. If dip soldered or hand soldered, its reliability cannot be guarantee.

Nitrogen reflow soldering is recommended. Air flow soldering conditions can cause optical degradation, caused by heat and/or atmosphere.





Above table specifies the maximum allowed duration and temperature during soldering. It is strongly advised to perform soldering at the shortest time and lowest temperature possible.

#### Cleaning:

Cleaning with isopropyl alcohol, propanol, or ethyl alcohol is recommended

DO NOT USE acetone, chloroseen, trichloroethylene, or MKS

DO NOT USE ultrasonic cleaners

#### **Static Electricity:**

**LEDs are sensitive to electrostatic discharge (ESD)**. Precautions against ESD must be taken when handling or operating these LEDs. Surge voltage or electrostatic discharge can result in complete failure of the device.

#### Radiation:

Those LEDs do emit **invisible light**, which is invisible and may cause cancer. Do avoid exposure to the emitted light. It is further advised to attach a warning label on products/systems.

#### Operation:

#### Do only operate LEDs with a current source.

Running these LEDs from a voltage source will result in complete failure of the device.

Current of a LED is an exponential function of the voltage across it. Usage of current regulated drive circuits is mandatory.

The above specifications are for reference purpose only and subjected to change without prior notice

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